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Mechanical standardization of semiconductor devices –

**Part 6-4:
General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of ball grid array (BGA)**

Normalisation mécanique des dispositifs à semiconducteurs –

*Partie 6-4:
Règles générales pour la préparation des dessins d'encombrement des dispositifs à semiconducteurs à montage en surface –
Méthodes de mesure pour les dimensions des boîtiers matriciels à billes*

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International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch

Commission Electrotechnique Internationale
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of ball grid array (BGA)

FOREWORD

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International Standard IEC 60191-6-4 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2006. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of ball grid array (BGA)

1 Scope

This part of IEC 60191 covers the requirements for the measuring methods of ball grid array (BGA) dimensions.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-6:1990, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*